



DFLU1400

PowerDl[®]123

Features

- Glass Passivated Die Construction
- Super-Fast Recovery Time for High Efficiency
- Low Forward-Voltage Drop and High Current Capability
- Patented Interlocking Clip Design for High Surge Capacity, US Patent #7,095,113
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: PowerDl[®]123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0

1.0A SURFACE MOUNT SUPER-FAST RECTIFIER

- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Weight: 0.011 grams (Approximate)



Ordering Information (Note 4)

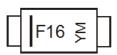
Device	Packaging	Shipping
DFLU1400-7	PowerDI [®] 123	3,000/Tape & Reel

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied. 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



F16 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Notes:

Date Cod	е Кеу													
Year	2005	2006	2007	2008	2009	2010	2011	2012	201	3 201	4 201	5 2016	2017	2018
Code	S	Т	U	V	W	Х	Y	Z	A	В	С	D	E	F
Mor	nth	Jan	Feb	Mar	Apr	May	Ju	n .	Jul	Aug	Sep	Oct	Nov	Dec
Co	de	1	2	3	4	5	6		7	8	9	0	N	D

See http://www and Lead-free.



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.			
Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 9)	V _{RRM} V _{RWM} V _R	400	V
RMS Reverse Voltage	V _{R(RMS)}	280	V
Average Rectified Output Current	lo	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	A

Thermal Characteristics

Characteristic		Symbol	Тур	Max	Unit
Power Dissipation (Note 5)	@T _A = +25°C	PD	—	1.0	W
Thermal Resistance Junction to Ambient (Note 5)	@T _A = +25°C	R _{0JA}	117	_	°C/W
Thermal Resistance Junction to Soldering Point (Not	Rejs	—	6	°C/W	
Operating and Storage Temperature Range	Tj, T _{STG}	-65 to	+150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Minimum Reverse Breakdown Voltage	@I _R =5μΑ	V _{(BR)R}	400	V
Maximum Forward Voltage Drop	@I _F = 1.0A	V _{FM}	1.25	V
Peak Reverse Current	@T _A = +25°C	le	5.0	
at Rated DC Blocking Voltage (Note 9)	@T _A = +100°C	IRM	200	μA
Maximum Reverse Recovery Time (Note 8)		t _{rr}	25	ns
Typical Total Capacitance (f = 1MHz, V_R = 4VDC)		CT	14	рF

5. Device mounted on 1" x 1", Polymide PCB; 2 oz. Cu pad layout as shown on Diodes Inc. suggested pad layout document AP02001.pdf. 6. RoHS revision 13.2.2003. Glass and high temperature solder exemptions applied; see *EU Directive Annex Notes 5 and 7*. Notes:

7. Theoretical $R_{\theta JS}$ calculated from the top center of the die straight down to the PCB cathode tab solder junction.

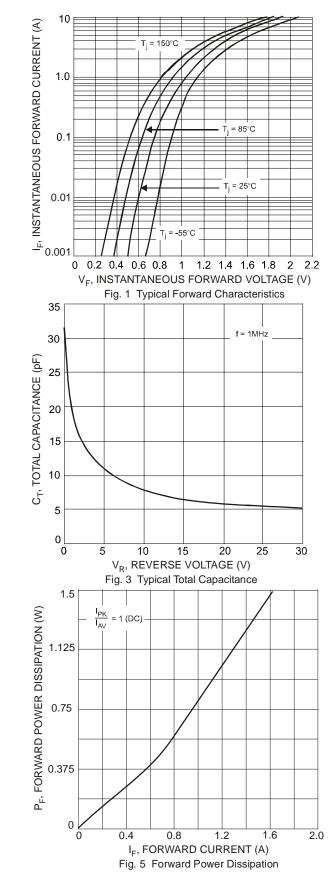
8. Measured with $I_F = 0.5A$, $I_R = 1.0A$, $I_{rr} = 0.25A$.

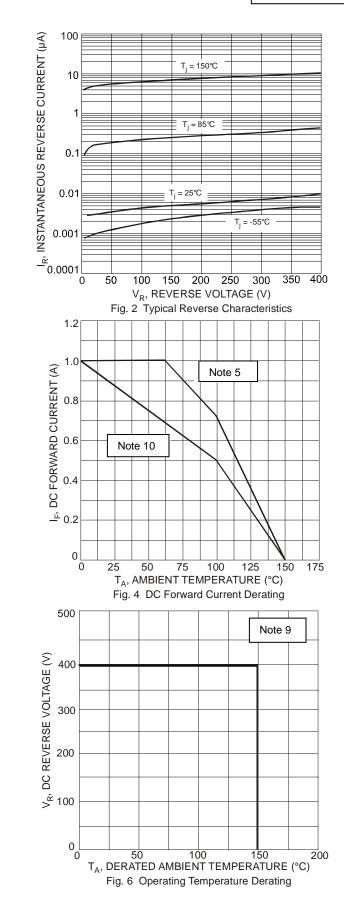
9. Short duration pulse test used to minimize self-heating effect.

10. Device mounted on FR-4 PCB, 2oz. Cu pad layout as shown on Diodes Inc. suggested pad layout document AP02001.pdf.





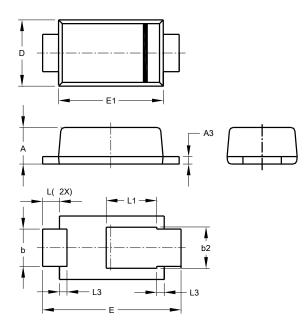






Package Outline Dimensions

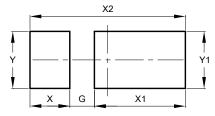
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



POWERDI [®] 123						
Dim	Min	Max	Тур			
Α	0.93	1.00	0.98			
A3	0.15	0.25	0.20			
b	0.85	1.25	1.00			
b2	1.025	1.125	1.10			
D	1.63	1.93	1.78			
Е	3.50	3.90	3.70			
E1	2.60	3.00	2.80			
L	0.40	0.50	0.45			
L1	1.25	1.40	1.35			
L3	0.125	0.275	0.20			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.65
Х	1.05
X1	2.40
X2	4.10
Ý	1.50
Y1	1.50



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